

Title (en)

MOUNTING AND POSITIONING MEANS FOR A PRINTHEAD DEVICE

Title (de)

MONTAGE- UND POSITIONIERVORRICHTUNG FÜR EINE DRUCKKOPFVORRICHTUNG

Title (fr)

DISPOSITIF DE MONTAGE ET DE POSITIONNEMENT POUR UN DISPOSITIF DE TÊTE D'IMPRESSION

Publication

EP 4389426 A1 20240626 (EN)

Application

EP 22216291 A 20221223

Priority

EP 22216291 A 20221223

Abstract (en)

The present invention provides a simple method for aligning droplet jetting devices when mounting these in a printer without the need for subsequent positional adjustment. The method comprising the steps of:- Providing a carrier (80) comprising a first planar mounting surface (82);- Providing a droplet jetting device (10) on the carrier (80) aligned with respect to the first planar mounting surface (82);- Providing on the first mounting surface (82) a plurality of mounting spheres (72) of a predetermined diameter, wherein each mounting sphere (72) is inserted into a circular holder (74), and wherein the holders (74) are adhered to the first mounting surface (82), such that the mounting spheres (72) are in direct contact with the first mounting surface (82).

IPC 8 full level

B41J 2/14 (2006.01); **B41J 25/34** (2006.01)

CPC (source: EP)

B41J 2/14233 (2013.01); **B41J 25/34** (2013.01); **B41J 2002/14241** (2013.01); **B41J 2002/14491** (2013.01); **B41J 2202/14** (2013.01); **B41J 2202/19** (2013.01); **B41J 2202/20** (2013.01)

Citation (applicant)

- US 7401899 B2 20080722 - NELLEN WILHELMUS H J [NL]
- US 10391768 B2 20190827 - REINTEN HANS [NL], et al

Citation (search report)

- [XAYI] US 2011316933 A1 20111229 - FISHKIN MIKHAIL [US], et al
- [Y] US 2014168293 A1 20140619 - MOREAU JEAN-MICHEL [CH], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC ME MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA

Designated validation state (EPC)

KH MA MD TN

DOCDB simple family (publication)

EP 4389426 A1 20240626; JP 2024091463 A 20240704

DOCDB simple family (application)

EP 22216291 A 20221223; JP 2023198513 A 20231122